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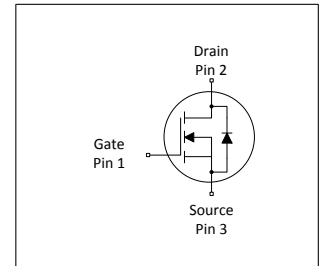
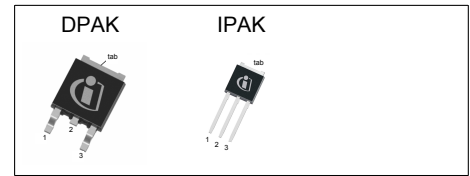
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# MOSFET

## 500V CoolMOS™ CE Power Transistor

CoolMOS™ is a revolutionary technology for high voltage power MOSFETs, designed according to the superjunction (SJ) principle and pioneered by Infineon Technologies. CoolMOS™ CE is a price-performance optimized platform enabling to target cost sensitive applications in Consumer and Lighting markets by still meeting highest efficiency standards. The new series provides all benefits of a fast switching Superjunction MOSFET while not sacrificing ease of use and offering the best cost down performance ratio available on the market.



### Features

- Extremely low losses due to very low FOM  $R_{DS(on)} \cdot Q_g$  and  $E_{oss}$
- Very high commutation ruggedness
- Easy to use/drive
- Pb-free plating, Halogen free mold compound
- Qualified for standard grade applications

### Applications

PFC stages, hard switching PWM stages and resonant switching stages for e.g. PC Silverbox, Adapter, LCD & PDP TV and indoor lighting.

*Please note: For MOSFET paralleling the use of ferrite beads on the gate or separate totem poles is generally recommended*



**Table 1 Key Performance Parameters**

Parameter	Value	Unit
$V_{DS} @ T_{j,max}$	550	V
$R_{DS(on),max}$	1.4	$\Omega$
$I_D$	4.8	A
$Q_{g,typ}$	8.2	nC
$I_{D,pulse}$	8.8	A
$E_{oss}@400V$	0.79	$\mu J$

Type / Ordering Code	Package	Marking	Related Links
IPD50R1K4CE	PG-TO 252	50S1K4CE	see Appendix A
IPU50R1K4CE	PG-TO 251		

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# 500V CoolMOS™ CE Power Transistor

## IPD50R1K4CE, IPU50R1K4CE

### 1 Maximum ratings

at  $T_j = 25^\circ\text{C}$ , unless otherwise specified

**Table 2 Maximum ratings**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Continuous drain current <sup>1)</sup>	$I_D$	-	-	4.8 3.1	A	$T_C = 25^\circ\text{C}$ $T_C = 100^\circ\text{C}$
Pulsed drain current <sup>2)</sup>	$I_{D,pulse}$	-	-	8.8	A	$T_C = 25^\circ\text{C}$
Avalanche energy, single pulse	$E_{AS}$	-	-	49	mJ	$I_D = 1.1\text{A}$ ; $V_{DD} = 50\text{V}$
Avalanche energy, repetitive	$E_{AR}$	-	-	0.07	mJ	$I_D = 1.1\text{A}$ ; $V_{DD} = 50\text{V}$
Avalanche current, repetitive	$I_{AR}$	-	-	1.1	A	-
MOSFET dv/dt ruggedness	dv/dt	-	-	50	V/ns	$V_{DS} = 0 \dots 400\text{V}$
Gate source voltage	$V_{GS}$	-20 -30	-	20 30	V	static; AC ( $f > 1\text{ Hz}$ )
Power dissipation (non FullPAK) TO-252, TO-251	$P_{tot}$	-	-	42	W	$T_C = 25^\circ\text{C}$
Operating and storage temperature	$T_j, T_{stg}$	-55	-	150	$^\circ\text{C}$	-
Continuous diode forward current	$I_S$	-	-	3.4	A	$T_C = 25^\circ\text{C}$
Diode pulse current <sup>2)</sup>	$I_{S,pulse}$	-	-	8.8	A	$T_C = 25^\circ\text{C}$
Reverse diode dv/dt <sup>3)</sup>	dv/dt	-	-	15	V/ns	$V_{DS} = 0 \dots 400\text{V}$ , $I_{SD} \leq I_S$ , $T_j = 25^\circ\text{C}$ , $t_{cond} < 2\mu\text{s}$
Maximum diode commutation speed <sup>3)</sup>	di/dt	-	-	500	A/ $\mu\text{s}$	$V_{DS} = 0 \dots 400\text{V}$ , $I_{SD} \leq I_S$ , $T_j = 25^\circ\text{C}$ , $t_{cond} < 2\mu\text{s}$

### 2 Thermal characteristics

**Table 3 Thermal characteristics DPAK, IPAK**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Thermal resistance, junction - case	$R_{thJC}$	-	-	2.95	$^\circ\text{C/W}$	-
Thermal resistance, junction - ambient <sup>4)</sup>	$R_{thJA}$	-	- 35	62 -	$^\circ\text{C/W}$	SMD version, device on PCB, minimal footprint SMD version, device on PCB, 6cm <sup>2</sup> cooling area <sup>4)</sup>
Soldering temperature, wave- & reflowsoldering allowed	$T_{sold}$	-	-	260	$^\circ\text{C}$	reflow MSL 1

<sup>1)</sup> Limited by  $T_{j,max}$ . Maximum duty cycle  $D=0.5$

<sup>2)</sup> Pulse width  $t_p$  limited by  $T_{j,max}$

<sup>3)</sup>  $V_{DClink}=400\text{V}$ ;  $V_{DS,peak} < V_{(BR)DSS}$ ; identical low side and high side switch with identical  $R_G$

<sup>4)</sup> Device on 40mm\*40mm\*1.5mm one layer epoxy PCB FR4 with 6cm<sup>2</sup> copper area (thickness 70 $\mu\text{m}$ ) for drain connection. PCB is vertical without air stream cooling.



### 3 Electrical characteristics

**Table 4 Static characteristics**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Drain-source breakdown voltage	$V_{(BR)DSS}$	500	-	-	V	$V_{GS}=0V, I_D=1mA$
Gate threshold voltage	$V_{(GS)th}$	2.50	3	3.50	V	$V_{DS}=V_{GS}, I_D=0.07mA$
Zero gate voltage drain current	$I_{DSS}$	-	-	1	$\mu A$	$V_{DS}=500V, V_{GS}=0V, T_j=25^\circ C$ $V_{DS}=500V, V_{GS}=0V, T_j=150^\circ C$
Gate-source leakage current	$I_{GSS}$	-	-	100	nA	$V_{GS}=20V, V_{DS}=0V$
Drain-source on-state resistance	$R_{DS(on)}$	-	1.26	1.40	$\Omega$	$V_{GS}=13V, I_D=0.9A, T_j=25^\circ C$ $V_{GS}=13V, I_D=0.9A, T_j=150^\circ C$
Gate resistance	$R_G$	-	7	-	$\Omega$	$f=1\text{ MHz, open drain}$

**Table 5 Dynamic characteristics**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Input capacitance	$C_{iss}$	-	178	-	pF	$V_{GS}=0V, V_{DS}=100V, f=1MHz$
Output capacitance	$C_{oss}$	-	11	-	pF	$V_{GS}=0V, V_{DS}=100V, f=1MHz$
Effective output capacitance, energy related <sup>1)</sup>	$C_{o(er)}$	-	10	-	pF	$V_{GS}=0V, V_{DS}=0...400V$
Effective output capacitance, time related <sup>2)</sup>	$C_{o(tr)}$	-	36	-	pF	$I_D=constant, V_{GS}=0V, V_{DS}=0...400V$
Turn-on delay time	$t_{d(on)}$	-	6.5	-	ns	$V_{DD}=400V, V_{GS}=13V, I_D=1.1A, R_G=5.3\Omega$
Rise time	$t_r$	-	6	-	ns	$V_{DD}=400V, V_{GS}=13V, I_D=1.1A, R_G=5.3\Omega$
Turn-off delay time	$t_{d(off)}$	-	23	-	ns	$V_{DD}=400V, V_{GS}=13V, I_D=1.1A, R_G=5.3\Omega$
Fall time	$t_f$	-	30	-	ns	$V_{DD}=400V, V_{GS}=13V, I_D=1.1A, R_G=5.3\Omega$

**Table 6 Gate charge characteristics**

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Gate to source charge	$Q_{gs}$	-	1	-	nC	$V_{DD}=400V, I_D=1.1A, V_{GS}=0\text{ to }10V$
Gate to drain charge	$Q_{gd}$	-	4.6	-	nC	$V_{DD}=400V, I_D=1.1A, V_{GS}=0\text{ to }10V$
Gate charge total	$Q_g$	-	8.2	-	nC	$V_{DD}=400V, I_D=1.1A, V_{GS}=0\text{ to }10V$
Gate plateau voltage	$V_{plateau}$	-	5.4	-	V	$V_{DD}=400V, I_D=1.1A, V_{GS}=0\text{ to }10V$

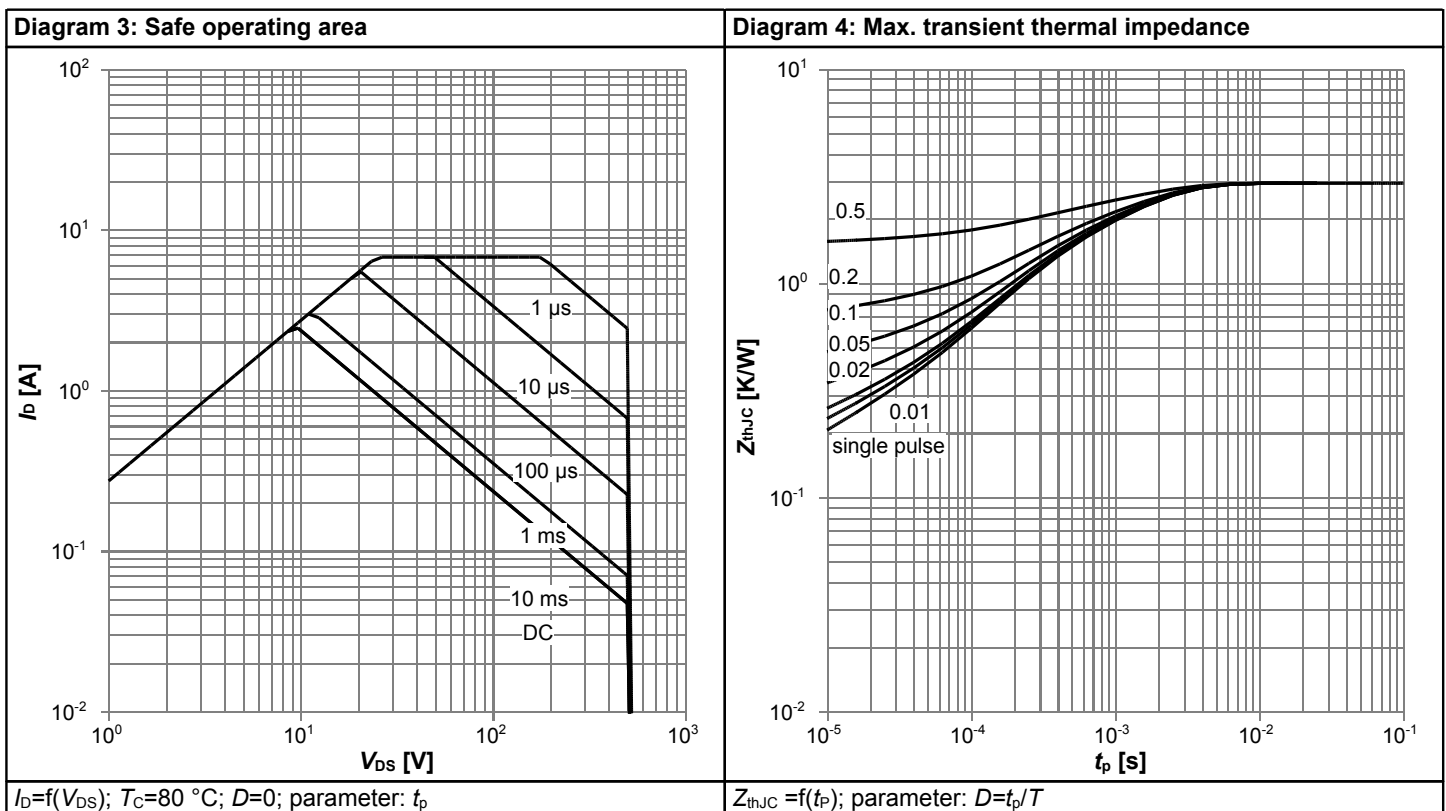
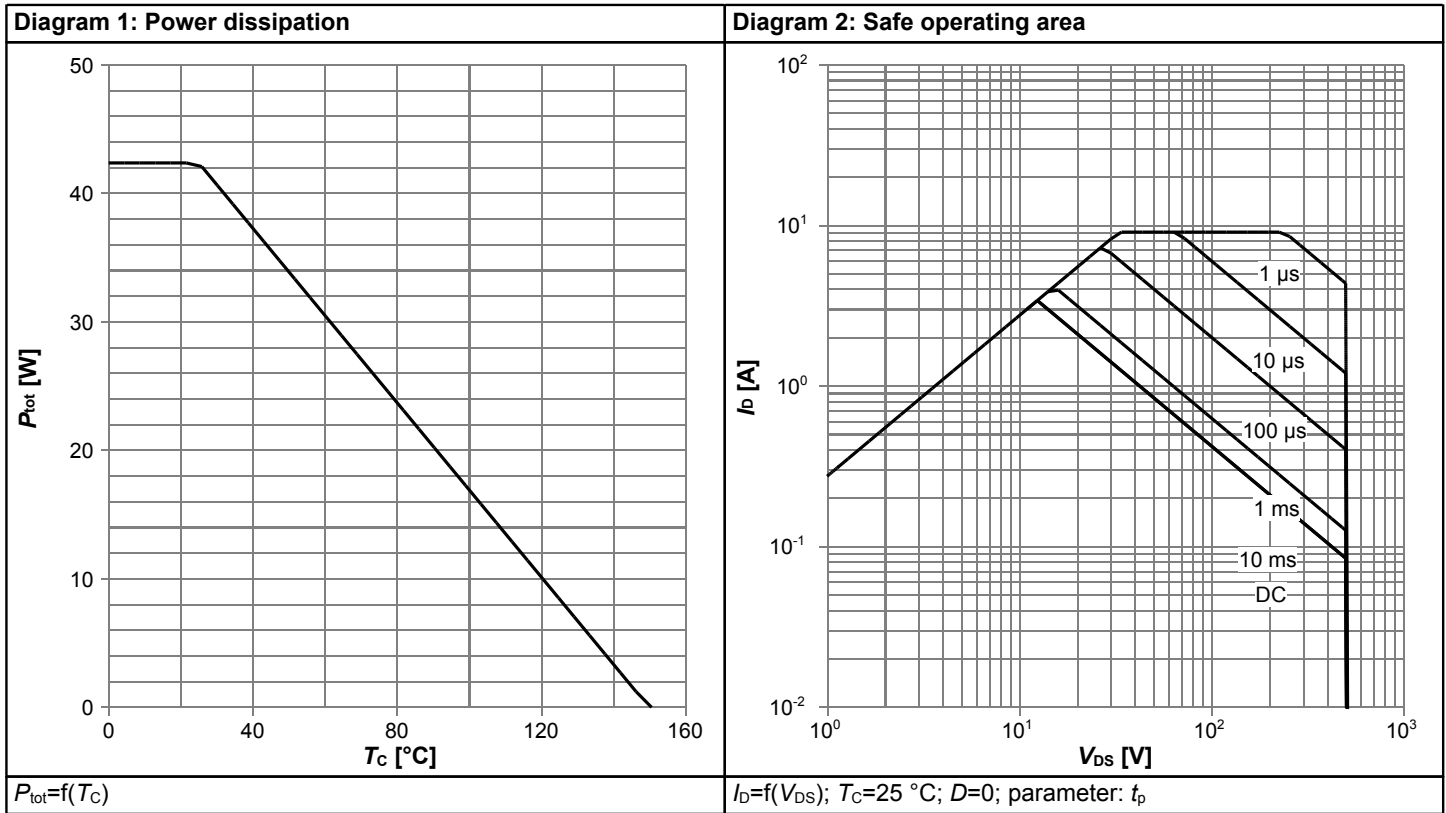
<sup>1)</sup>  $C_{o(er)}$  is a fixed capacitance that gives the same stored energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 to 80%  $V_{(BR)DSS}$

<sup>2)</sup>  $C_{o(tr)}$  is a fixed capacitance that gives the same charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 to 80%  $V_{(BR)DSS}$

**Table 7 Reverse diode characteristics**

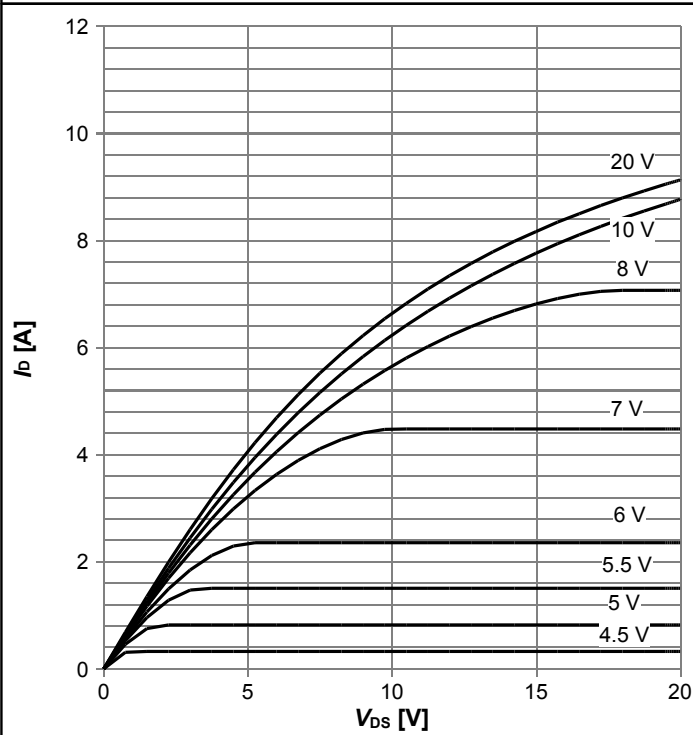
Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Diode forward voltage	$V_{SD}$	-	0.83	-	V	$V_{GS}=0V, I_F=1.1A, T_i=25^{\circ}C$
Reverse recovery time	$t_{rr}$	-	120	-	ns	$V_R=400V, I_F=1.1A, di_F/dt=100A/\mu s$
Reverse recovery charge	$Q_{rr}$	-	0.5	-	$\mu C$	$V_R=400V, I_F=1.1A, di_F/dt=100A/\mu s$
Peak reverse recovery current	$I_{rrm}$	-	6.8	-	A	$V_R=400V, I_F=1.1A, di_F/dt=100A/\mu s$

## 4 Electrical characteristics diagrams



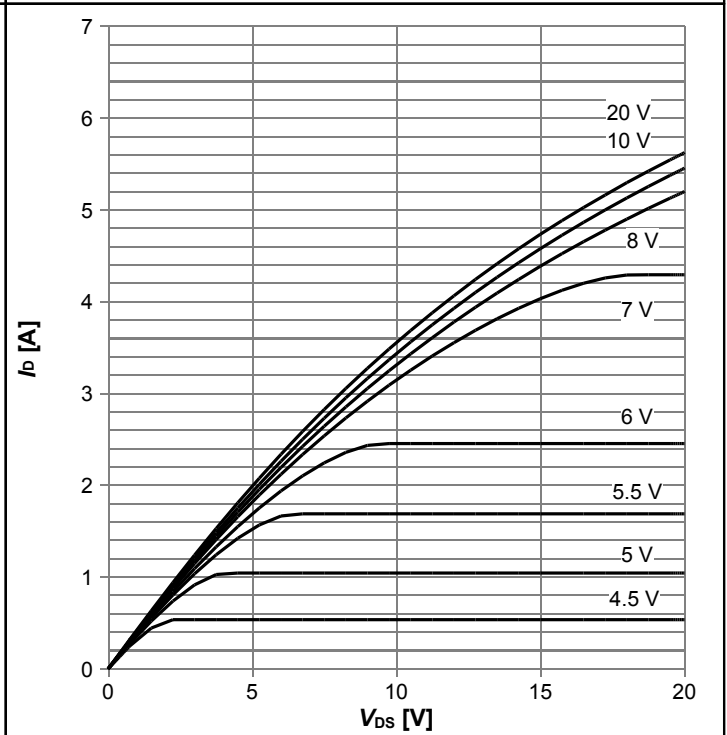
**500V CoolMOS™ CE Power Transistor**  
**IPD50R1K4CE, IPU50R1K4CE**

**Diagram 5: Typ. output characteristics  $T_j=25^\circ\text{C}$**



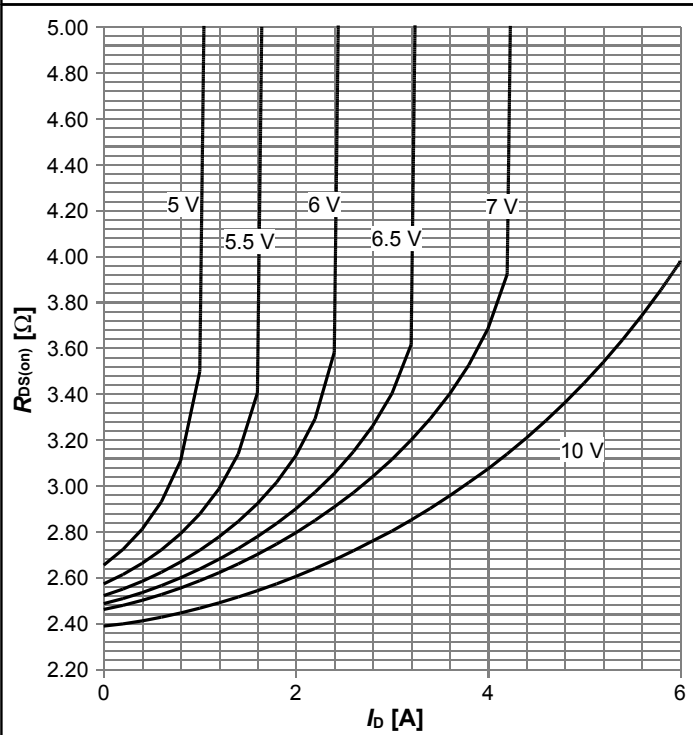
$I_D=f(V_{DS})$ ;  $T_j=25^\circ\text{C}$ ; parameter:  $V_{GS}$

**Diagram 6: Typ. output characteristics  $T_j=125^\circ\text{C}$**



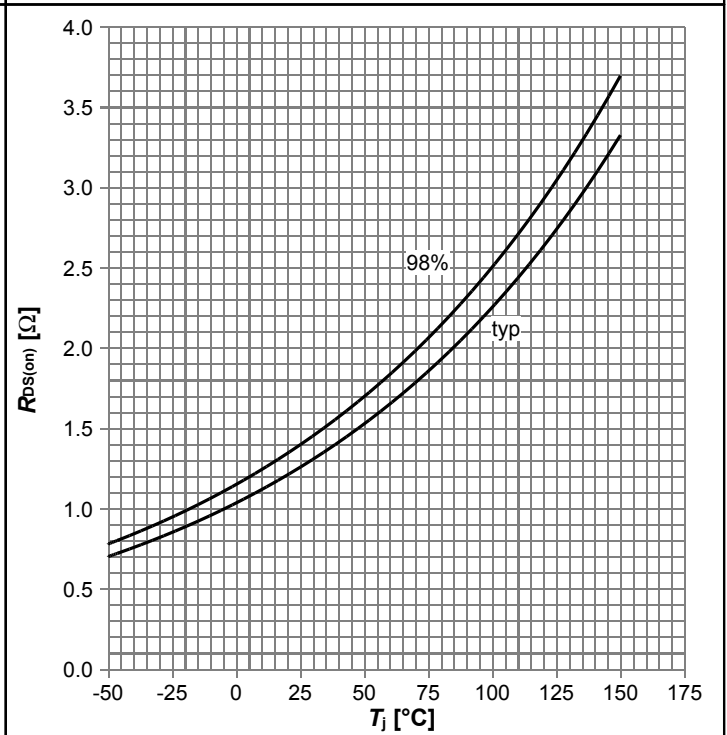
$I_D=f(V_{DS})$ ;  $T_j=125^\circ\text{C}$ ; parameter:  $V_{GS}$

**Diagram 7: Typ. drain-source on-state resistance**



$R_{DS(on)}=f(I_D)$ ;  $T_j=125^\circ\text{C}$ ; parameter:  $V_{GS}$

**Diagram 8: Drain-source on-state resistance**

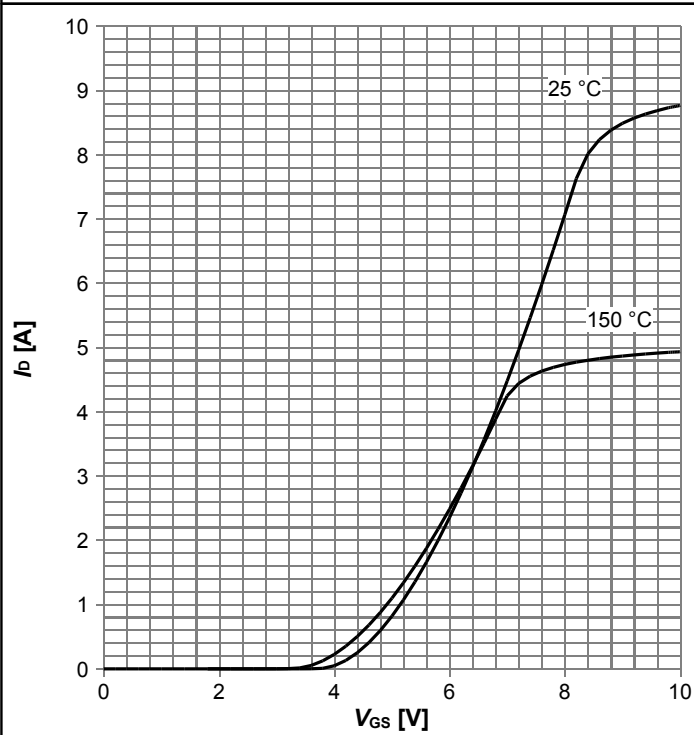


$R_{DS(on)}=f(T_j)$ ;  $I_D=0.9\text{ A}$ ;  $V_{GS}=13\text{ V}$



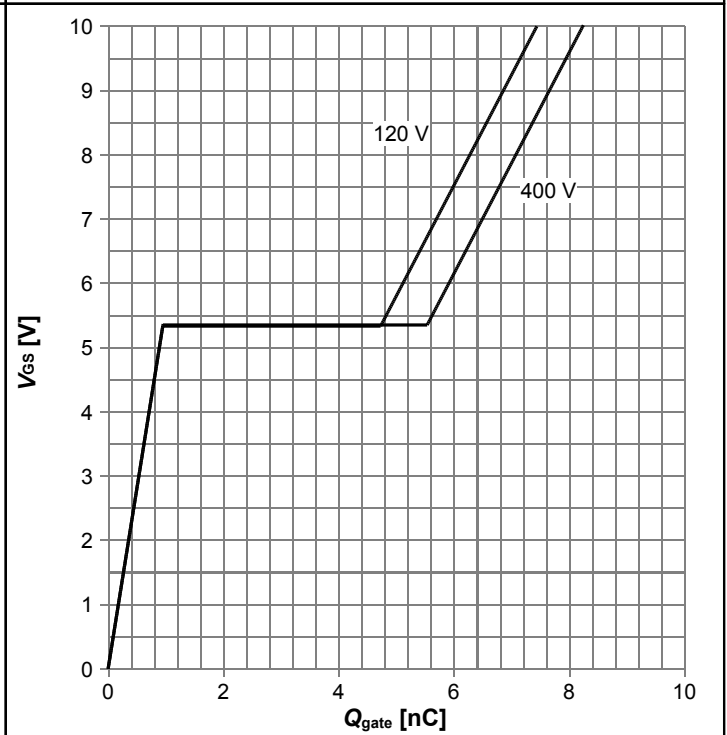
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**Diagram 9: Typ. transfer characteristics**



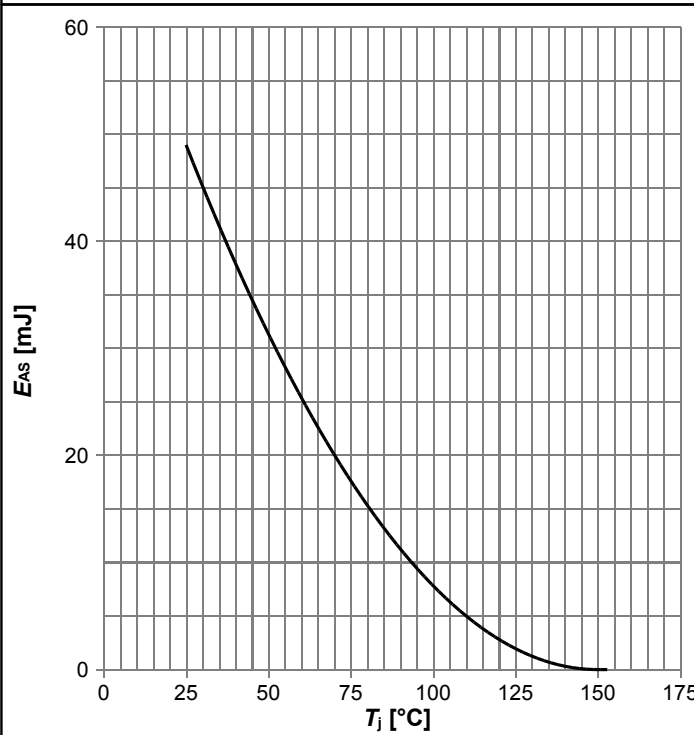
$I_D = f(V_{GS}); V_{DS} = 20V; \text{parameter: } T_j$

**Diagram 10: Typ. gate charge**



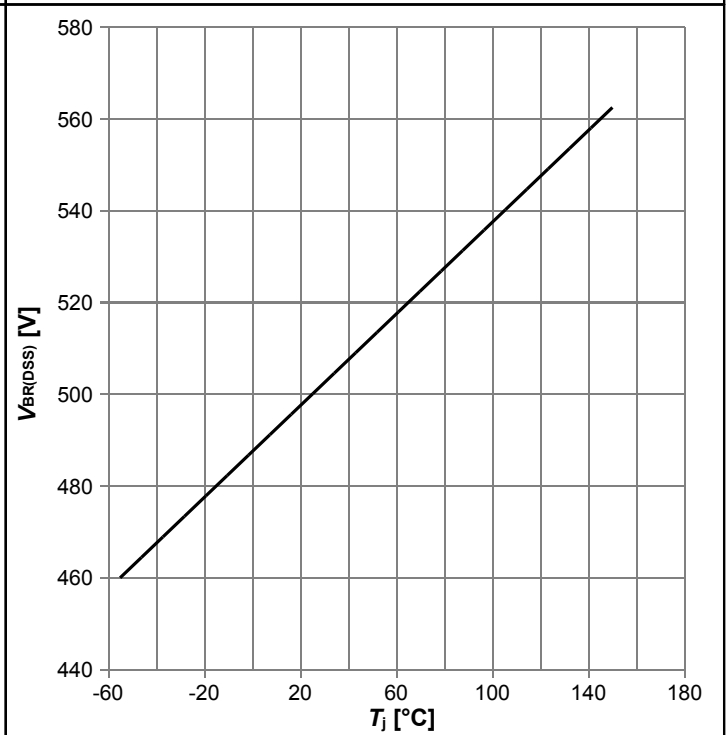
$V_{GS} = f(Q_{gate}); I_D = 1.1 \text{ A pulsed}; \text{parameter: } V_{DD}$

**Diagram 11: Avalanche energy**



$E_{AS} = f(T_j); I_D = 1.1 \text{ A}; V_{DD} = 50 \text{ V}$

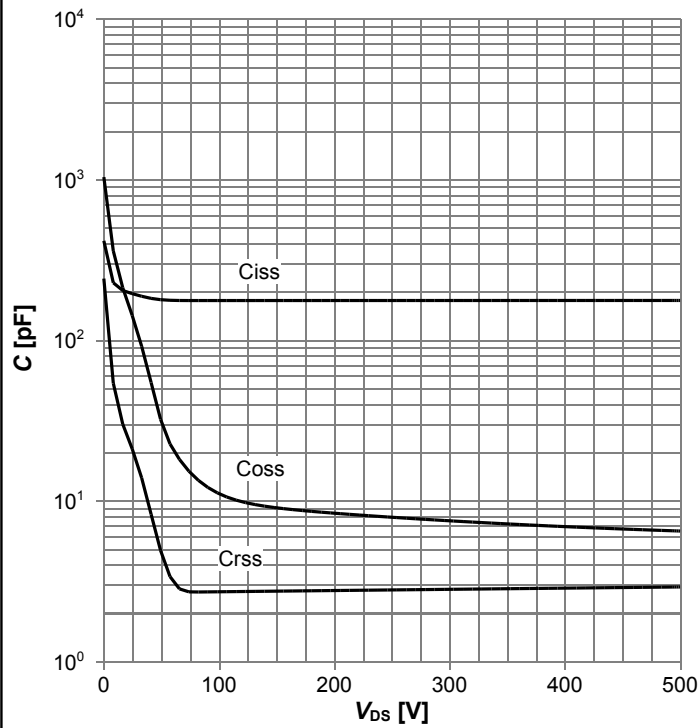
**Diagram 12: Drain-source breakdown voltage**



$V_{BR(DSS)} = f(T_j); I_D = 1 \text{ mA}$

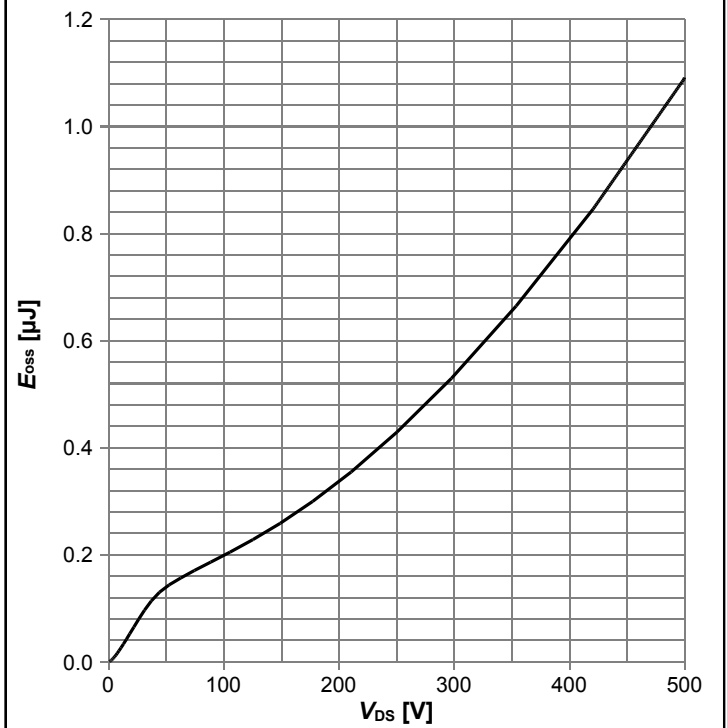
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**Diagram 13: Typ. capacitances**



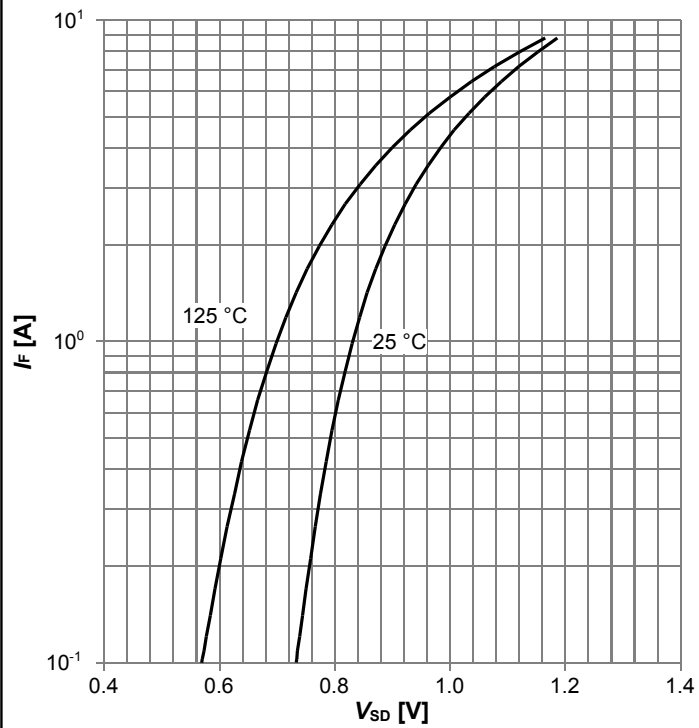
$C=f(V_{Ds}); V_{GS}=0\text{ V}; f=1\text{ MHz}$

**Diagram 14: Typ. Coss stored energy**



$E_{oss}=f(V_{Ds})$

**Diagram 15: Forward characteristics of reverse diode**



$I_F=f(V_{SD}); \text{parameter: } T_j$

## 5 Test Circuits

**Table 8 Diode characteristics**

Test circuit for diode characteristics	Diode recovery waveform
<p><math>R_{g1} = R_{g2}</math></p>	<p><math>t_{tr} = t_F + t_S</math>  <math>Q_{tr} = Q_F + Q_S</math></p>

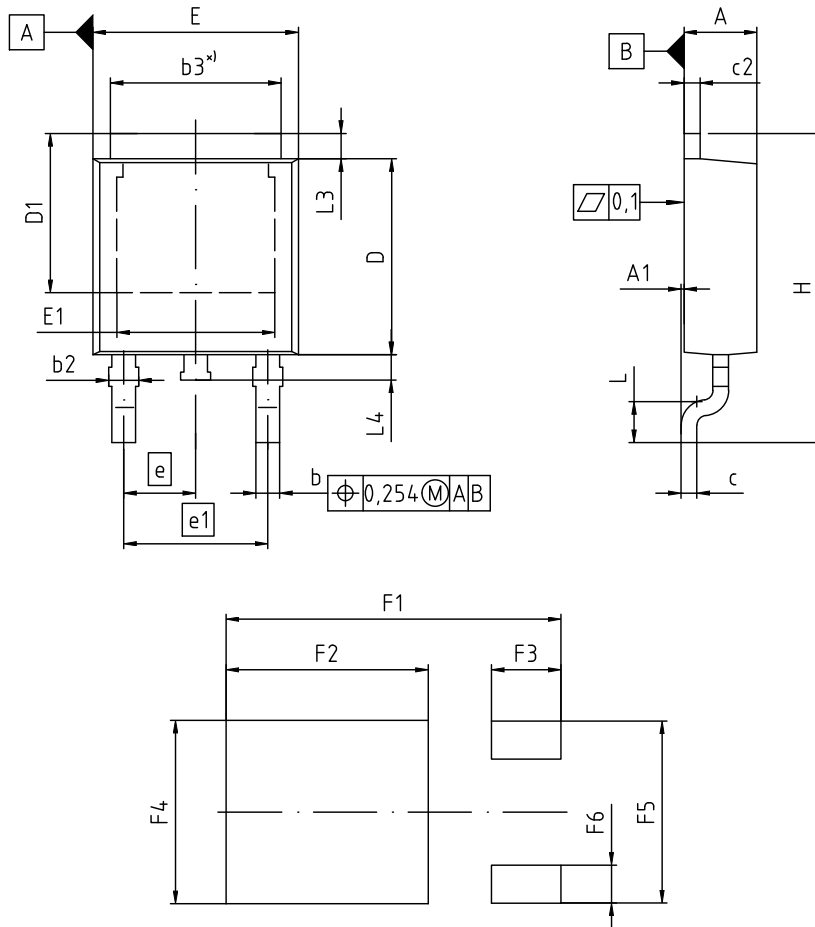
**Table 9 Switching times**

Switching times test circuit for inductive load	Switching times waveform

**Table 10 Unclamped inductive load**

Unclamped inductive load test circuit	Unclamped inductive waveform

## 6 Package Outlines



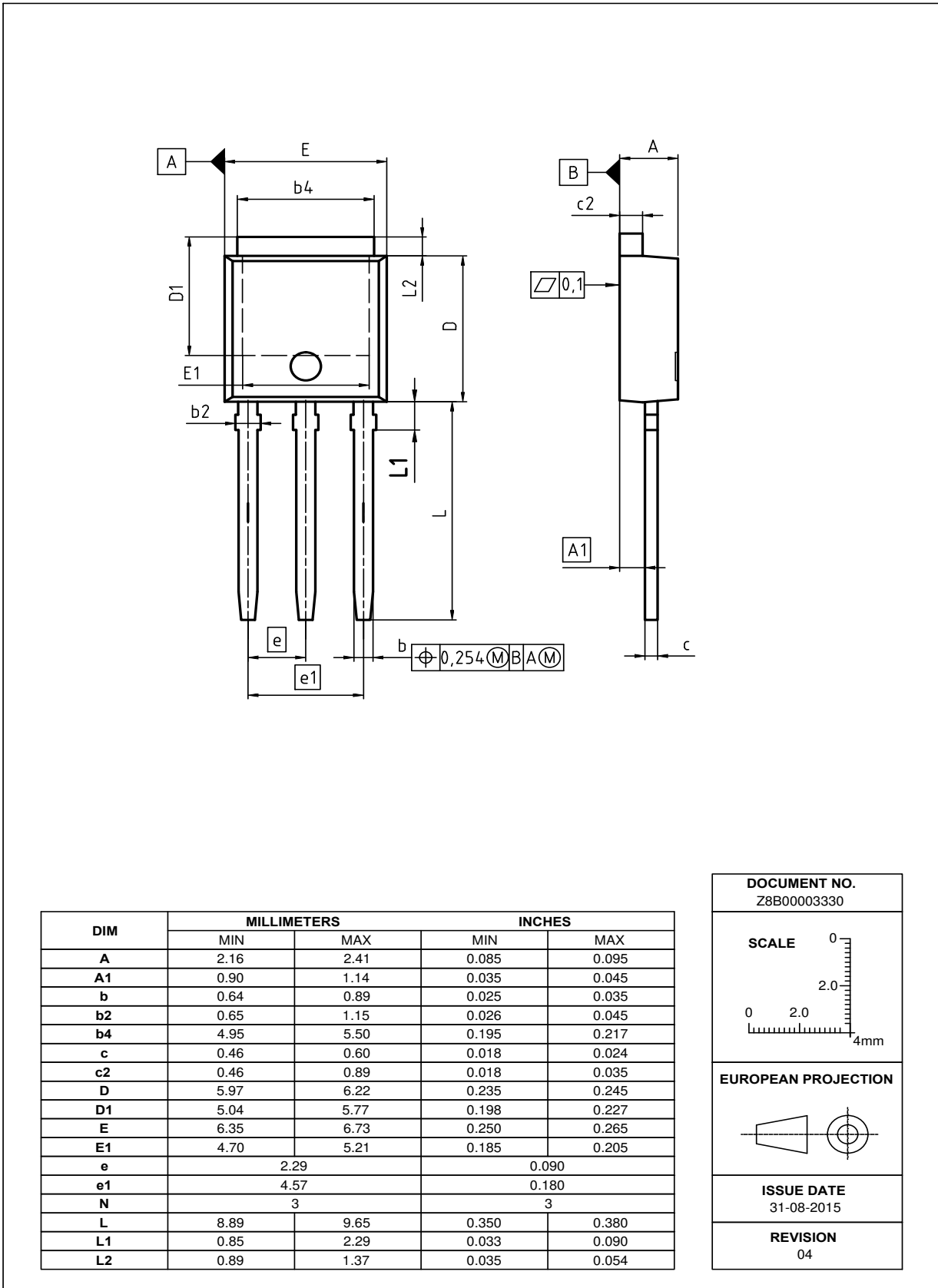
\*) mold flash not included

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.16	2.41	0.085	0.095
A1	0.00	0.15	0.000	0.006
b	0.64	0.89	0.025	0.035
b2	0.65	1.15	0.026	0.045
b3	5.00	5.50	0.197	0.217
c	0.46	0.60	0.018	0.024
c2	0.46	0.98	0.018	0.039
D	5.97	6.22	0.235	0.245
D1	5.02	5.84	0.198	0.230
E	6.40	6.73	0.252	0.265
E1	4.70	5.60	0.185	0.220
e	2.29 (BSC)		0.090 (BSC)	
e1	4.57 (BSC)		0.180 (BSC)	
N	3		3	
H	9.40	10.48	0.370	0.413
L	1.18	1.70	0.046	0.067
L3	0.90	1.25	0.035	0.049
L4	0.51	1.00	0.020	0.039
F1	10.60		0.417	
F2	6.40		0.252	
F3	2.20		0.087	
F4	5.80		0.228	
F5	5.76		0.227	
F6	1.20		0.047	

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**Figure 1 Outline PG-TO 252, dimensions in mm/inches**

**500V CoolMOS™ CE Power Transistor**  
**IPD50R1K4CE, IPU50R1K4CE**



**Figure 2 Outline PG-TO 251, dimensions in mm/inches**

## 7 Appendix A

### Table 11 Related Links

- IFX CoolMOS Webpage: [www.infineon.com](http://www.infineon.com)
- IFX Design tools: [www.infineon.com](http://www.infineon.com)



# 500V CoolMOS™ CE Power Transistor

## IPD50R1K4CE, IPU50R1K4CE

### Revision History

IPD50R1K4CE, IPU50R1K4CE

**Revision: 2016-06-13, Rev. 2.4**

Previous Revision

Revision	Date	Subjects (major changes since last revision)
2.0	2012-09-13	Release of final version
2.1	2012-12-05	release of final datasheet
2.2	2013-07-16	update to Halogen free mold compound
2.3	2015-11-17	Updated to standard grade qualified & updated package drawing
2.4	2016-06-13	Updated ID ratings, Zth, SOA and Pd curves

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